



BSI Standards Publication

Semiconductor devices — Micro-electromechanical devices

Part 38: Test method for adhesion strength of metal powder paste in MEMS interconnection

National foreword

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The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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INTERNATIONAL STANDARD



**Semiconductor devices – Micro-electromechanical devices –
Part 38: Test method for adhesion strength of metal powder paste in MEMS
interconnection**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MICRO-ELECTROMECHANICAL DEVICES –****Part 38: Test method for adhesion strength of
metal powder paste in MEMS interconnection****FOREWORD**

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Full information on the voting for its approval can be found in the report on voting indicated in the above table.

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